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J1000 U.S. PTO

09/852824



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Charles W.C. Lin
Title: BUMPLESS FLIP CHIP ASSEMBLY WITH SOLDER VIA
Serial No.: Unknown Filed: Herewith
Examiner: Unknown Group Art Unit: Unknown
Atty. Docket No.: P002-2

ASSISTANT COMMISSIONER FOR PATENTS
Washington, D.C. 20231

INFORMATION DISCLOSURE STATEMENT

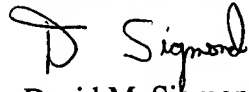
Pursuant to Applicant's duty of disclosure under 37 C.F.R. § 1.56 and §§ 1.97-1.98,
Applicant hereby submits the enclosed Form PTO-1449.

Copies of documents cited on the enclosed Form PTO-1449 are not enclosed because
they were previously cited by or submitted to the U.S. Patent Office in prior U.S. Application
Serial No. 09/465,024 filed December 16, 1999. The above-identified application is a divisional
of the prior application.

The filing of this Information Disclosure Statement shall not be construed as a
representation that a search has been made, an admission that any of these documents, alone or in
any combination, is considered to be material to patentability, an admission that any of these
documents is prior art as to the above-identified application, or an admission against interest in
any manner.

This Information Disclosure Statement is filed before the mailing date of a first Office
Action. Accordingly, no fee is due.

Respectfully submitted,

A handwritten signature in black ink, appearing to read "D Sigmond". The signature is written in a cursive, flowing style.

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